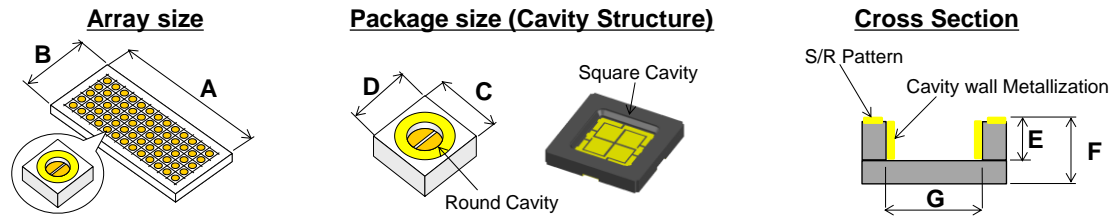


KYOCERA MULTILAYER CERAMIC PACKAGES for LED



Unit : mm

R0316A

No.	MATERIAL (CODE)	DIE ATTACH AREA THERMAL CONDUCTIVITY	DRAWING NO.	DESIGN	ARRAY SIZE A x B	PACKAGE SIZE C x D	CAVITY(DEPTH) E	THICKNESS F	CAVITY SIZE G	S/R PATTERN	CAVITY WALL METALLIZATION	CAVITY STRUCTURE	PLATING	PCS/ARRAY	NOTES (*)
1	AlN (AN242)	AlN:150W/mK	KD-LB7248		58.8 x 45.5	3.45SQ	0.40	0.8	2.40SQ	With	Without	Square Cavity	Ni-Au	130pcs/Array	F/C Model
2	AlN (AN242)	AlN:150W/mK	KD-LB7E07		58.8 x 45.5	3.45SQ	0.40	0.8	2.40SQ	Without	Without	Square Cavity	Ni-Au	130pcs/Array	F/C Model
3	AlN (AN242)	AlN:150W/mK	KD-LB6T90		58.8 x 45.5	3.45SQ	0.60	0.9	2.40SQ	With	Without	Square Cavity	Ni-Au	130pcs/Array	W/B Model
4	AlN (AN242)	AlN:150W/mK	KD-LB7319		58.8 x 45.5	6.8SQ	0.40	1.0	(4.90dia.)	With	Without	Round Cavit	Ni-Au	35pcs/Array	Multi Chip Model

(* W/B : Wire Bond , F/C : Flip Chip)